

5 é / Descriptions

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N-Channel Enhancement Mode Field Effect Transistor in a DFN3 ~3A-8L Plastic Package.

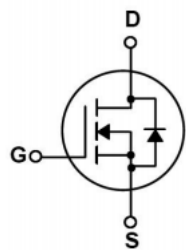
□ ª / Features

V_{DS} (V) = 20V I_D = 43A (V_{GS} = f 12V)
R_{DS(ON)}@10V 0 10m S(Typ.8.0m S)
R_{DS(ON)}@4.5V 0 11m S(Typ.9.5m S)
R_{DS(ON)}@2.5V 0 16m S(Typ.14m S)
—)í D } ožHF Product.

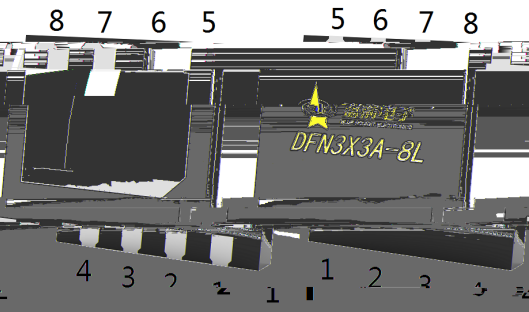
Đ ÷ / Applications

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Suited for low voltage applications such as automotive, DC/DC Converters, and high efficiency switching for power management in portable and battery operated products.

Ã W] Ô · / Equivalent Circuit



• Ů - æ / Pinning



出脚	定义
Pin1	S
Pin2	S
Pin3	S
Pin4	G
Pin5	D
Pin6	D
Pin7	D
Pin8	D

, M V / Marking

• - ~ ª ¢ož
See Marking Instructions.

1. Absolute Maximum Ratings(Ta=25℃ ;)

Symbol	Unit	Value
V_{DS}	V	20
I_{DS}	A	1.0
I_{GSS}	A	±0.1
$R_{DS(on)}$	mΩ	8~16
$V_{GS(th)}$	V	0.5~1.1
V_{SD}	V	1.2
R_g	Ω	2.7
C_{iss}	pF	1100
C_{oss}	pF	160
C_{rss}	pF	130

2. Electrical Characteristics(Ta=25℃ ;)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V$ $I_D=250\mu A$	20	25		V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=20V$ $V_{GS}=0V$			1.0	A
Gate-Body Leakage Current Forward	I_{GSS}	$V_{GS}=\pm 12V$ $V_{DS}=0V$			±0.1	A
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V$ $I_D=10.0A$		8	10	mΩ
		$V_{GS}=4.5V$ $I_D=10.0A$		9.5	11	mΩ
		$V_{GS}=2.5V$ $I_D=10.0A$		14	16	mΩ
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ $I_D=250\mu A$	0.5	0.8	1.1	V
Drain-Source Diode Forward Voltage	V_{SD}	$V_{GS}=0V$ $I_F=1.0A$		0.75	1.2	V
Signal Source Resistance	R_g	$F=1MHz$		2.7		Ω
Input Capacitance	C_{iss}	$V_{DS}=15V$ $V_{GS}=0V$ $f=1.0MHz$		1100		pF
Output Capacitance	C_{oss}			160		
Reverse Transfer Capacitance	C_{rss}			130		

Electrical Characteristics(Ta=25℃ ;)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Turn-On Delay Time	t _{d(on)}	V _{DS} =10V V _{GS} =10V R _L =1.0 R _{GEN} =3.0		2.5		ns
Turn-On Rise Time	t _r			7.2		
Turn-Off Delay Time	t _{d(off)}			49		
Turn-Off Fall Time	t _f			10.8		
Total Gate Charge	Q _{g(4.5V)}	V _{DS} =10V V _{GS} =4.5V I _D =12.0A		17.9		nC
Gate-Source Charge	Q _{gs}			1.5		
Gate-Drain Charge	Q _{gd}			4.7		

Electrical Characteristic Curve

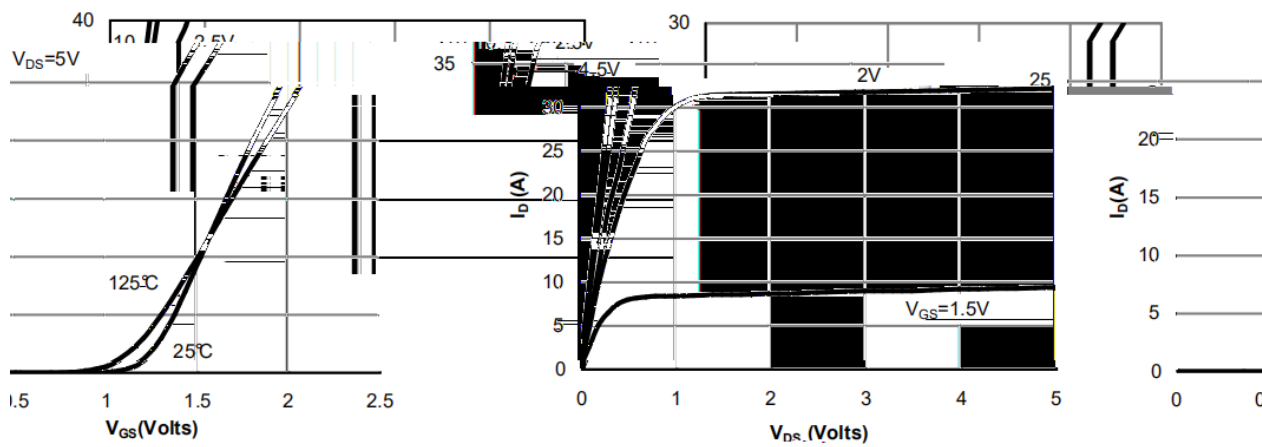


Figure 2: Transfer Characteristics

Figure 1: On-Region Characteristics

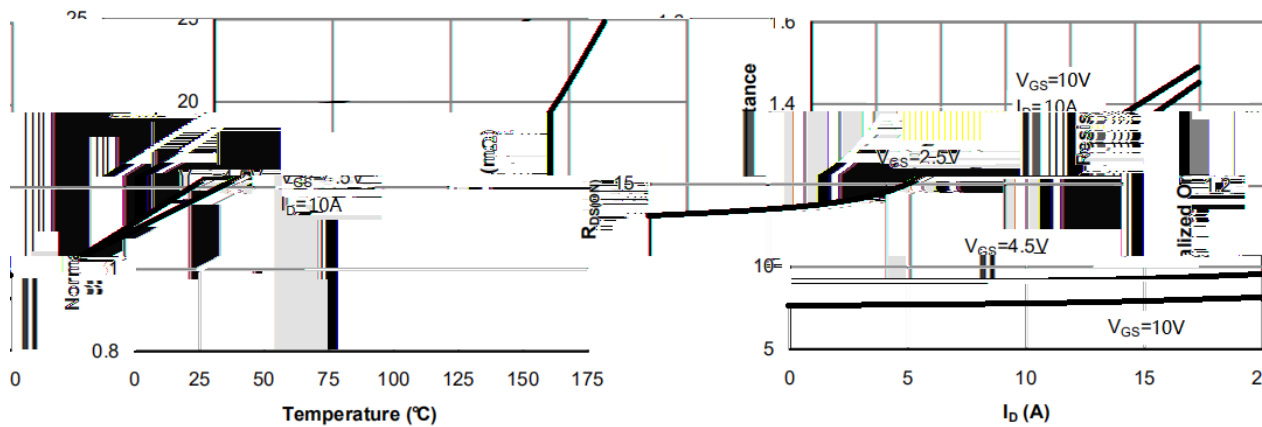


Figure 4: On-Resistance vs. Junction Temperature

Figure 3: On-Resistance vs. Drain Current and Gate Voltage

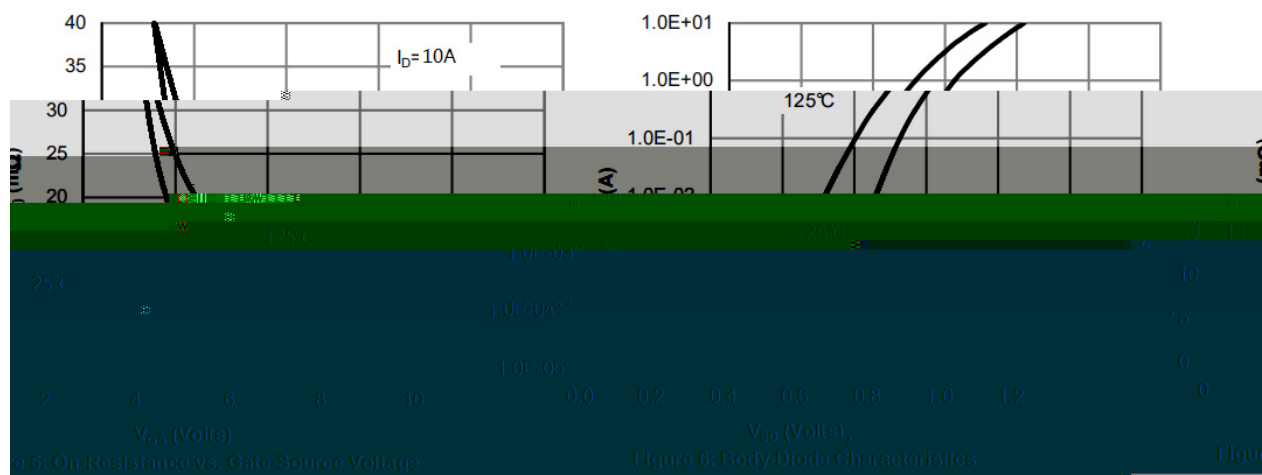
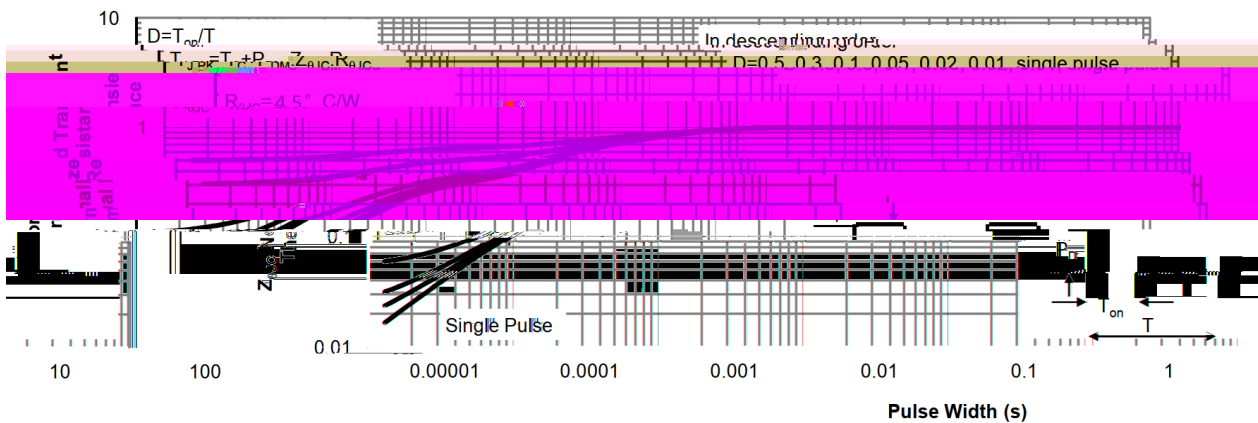
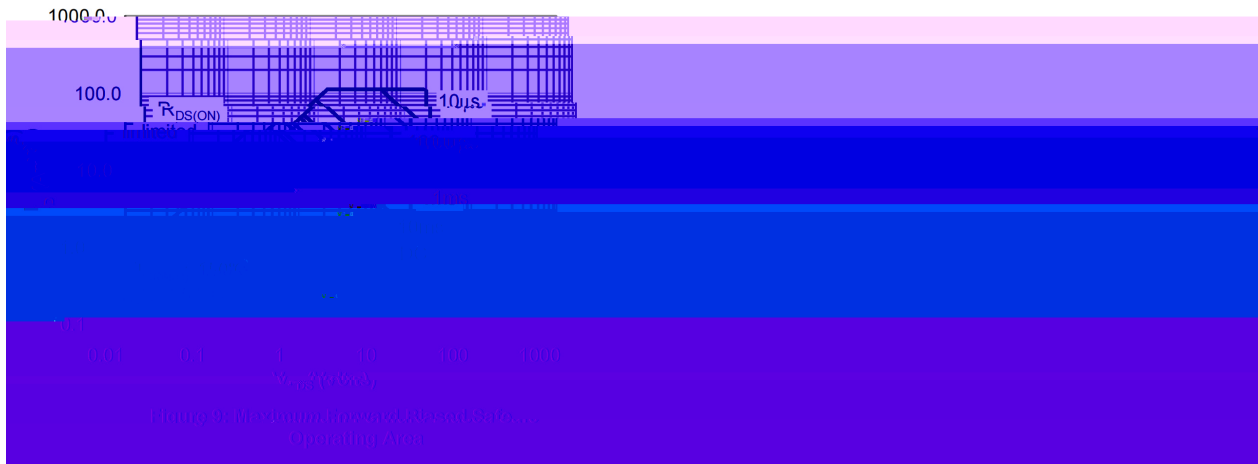
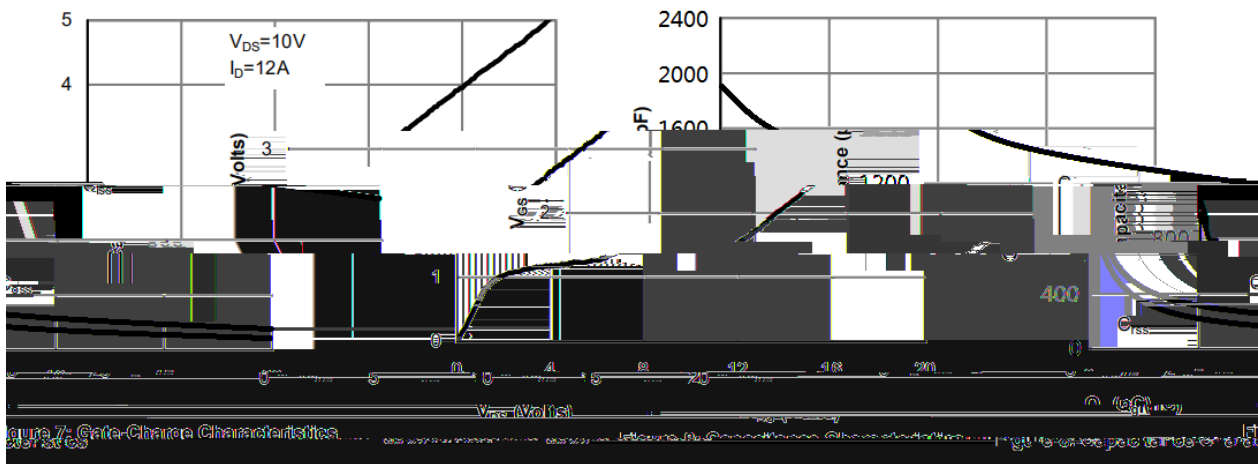


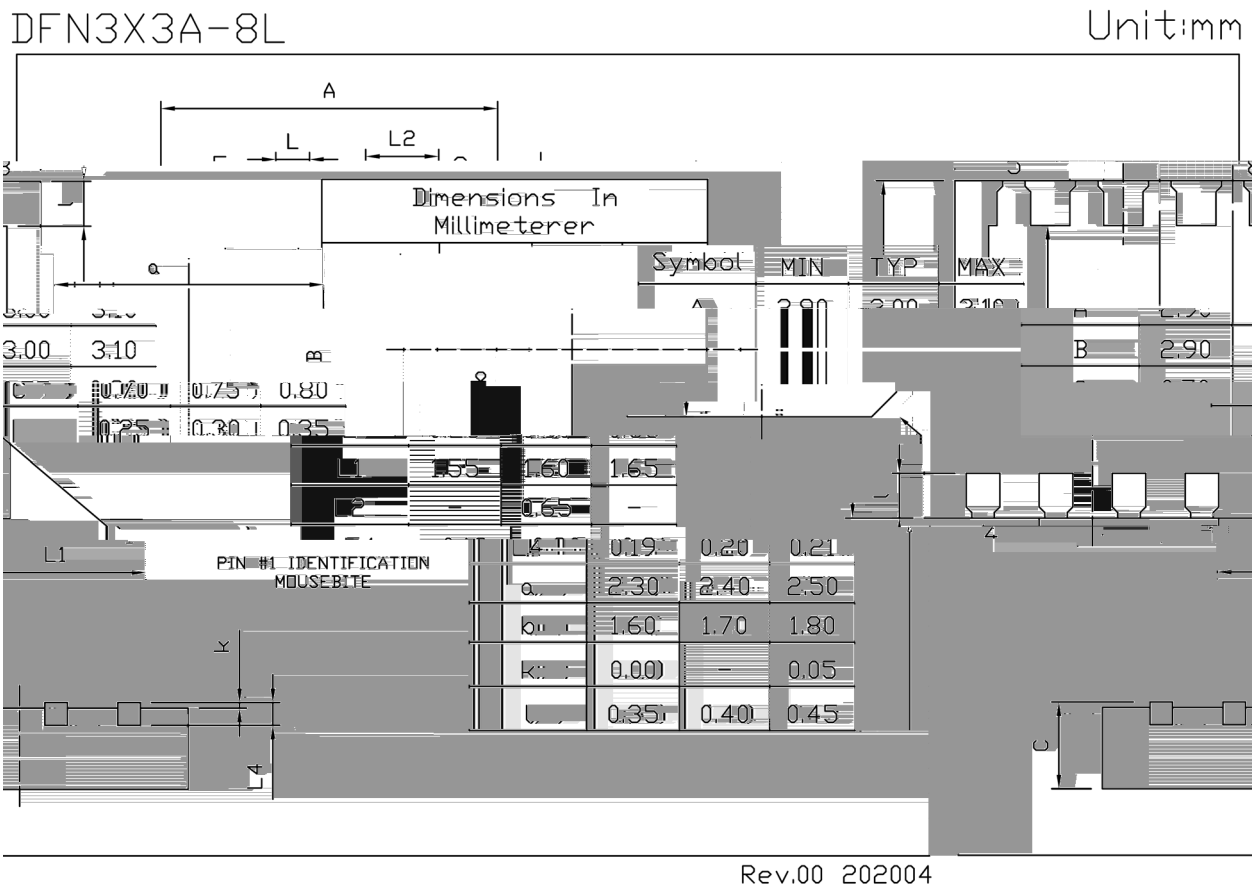
Figure 5: On-Resistance vs. Gate-Source Voltage

Figure 6: Body Diode Characteristics

Electrical Characteristic Curve



Ø □ =) ☎ / Package Dimensions



, M y f / Marking Instructions



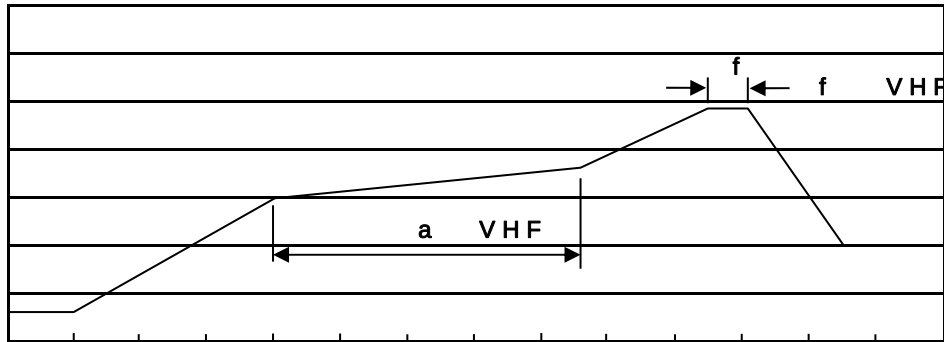
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BR y , [W A
080N02 y ° Z W A
**** y ÿ D Z W A k š ÿ D Z J

Note:
BR: Company Code
080N02: Product Type Code
****: Lot No. Code, code change with Lot No



šWD t...•Žč (x/) / :KSVKXGZ[XK 6XULORK LUX /8 8KLRU] 9URJKXOTM 6

7HPSHUDWXUH



7LPH VHF

a č y

10• Ä ½ “† 150 ½180 - k ž • 60 ½90sec;

20• Q > “† 245 r5 - k ž • 4 Ò 5 r0.5sec;

30•D N ò i Ò 0 ,† 2 ½10 - /sec.

Note:

1.Preheating:150~180 - , Time:60~90sec.

2.Peak Temp.:245 r5 - , Duration:5 r0.5sec.

3. Cooling Speed: 2~10 - /sec.

ÂD /Că p ¯ »] / Resistance to Soldering Heat Test Conditions

“† y 260 r5 -

ž • y 10 r1 sec.

Temp.:260±5

Time:10±1 sec

G P á / Packaging SPEC.

2 & x / REEL

Package Type 7>û ~ E	Units ;>û H					Dimension ;>û p . (unit Åmm³)		
	Units/Reel /-	Reels/Inner Box -- /-	Units/Inner Box /-	Inner Boxes/Outer Box - /1ç	Units/Outer Box /1ç	Reel	Inner Box	Outer Boxç
DFN3×3A-8L	5,000	2	10,000	6	60,000	13 s ×12	360×360×50	380×335×366

„Đ y f / Notices